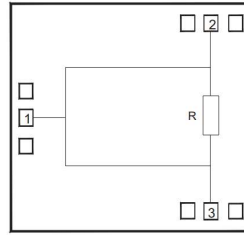


Performance

- Frequency: 1~3GHz
- Insertion loss: 0.7dB
- Chip size: 1.40*1.12*0.1mm

Function Diagram

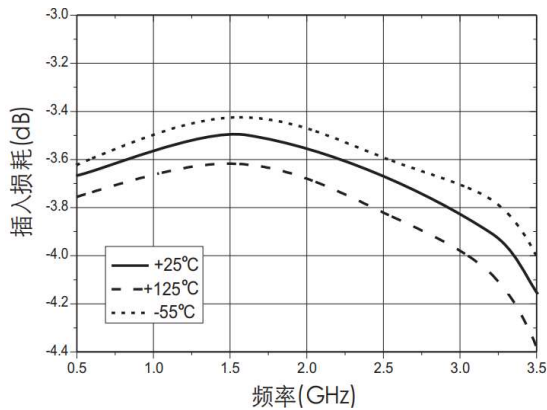


Electrical Specifications (Ta=+25°C, 50Ω system)

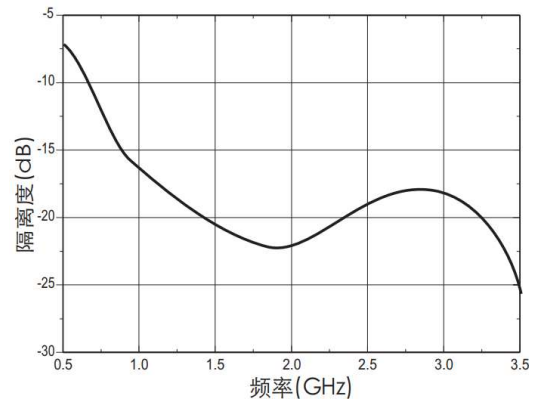
Parameter	Min	Typical	Max	Unit
Frequency Range	1~3			GHz
Insertion Loss	-	0.7	0.9	dB
Insertion Loss Ripple	-	±0.2	-	dB
Isolation	15	18	-	dB
Input Return Loss	14	18	-	dB
Output Return Loss	18	22	-	dB

Test Curves

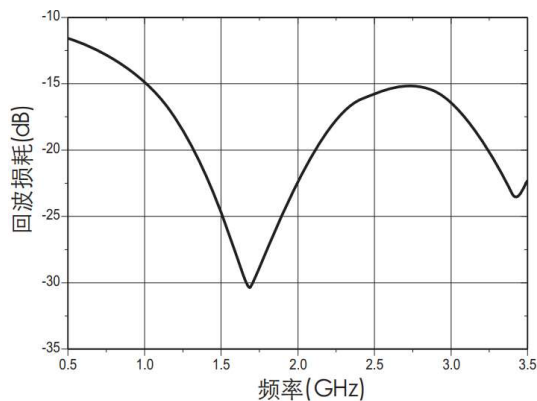
Insertion loss vs. Freq



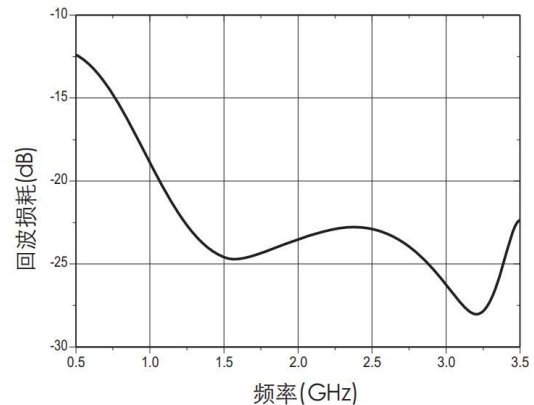
Isolation vs. Freq



Input Return Loss vs. Freq



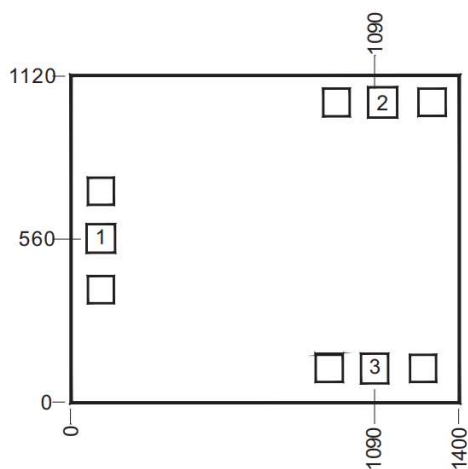
Output Return Loss vs. Freq



Absolute Max Ratings

Parameter	Value
Input Signal Power	+37dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C
Junction Temperature	175°C
Static protection Grade (HBM)	Class 1A

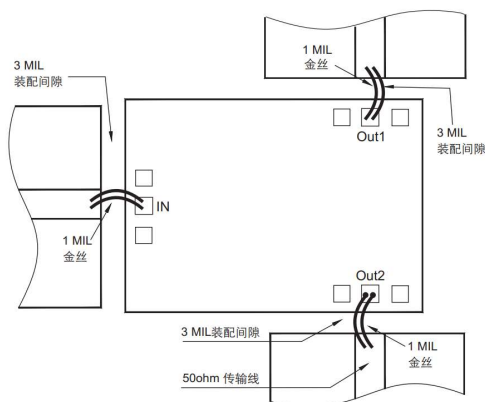
Outline Size



Note:

1. Unit: μm
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated
Pads size: $100 \times 100 \mu\text{m}$
5. Don't bonding on thru holds
6. Tolerance: $\pm 50 \mu\text{m}$

Assembly Diagram



Bonding Definition

Number	Description
IN	RF input port, connect to 50ohm system
Out1 Out2	RF output port, connect to 50ohm system
GND	Bottom must be grounded